

N-Channel MOSFET

General Description

The WSK40200 use advanced SGT MOSFET technology to provide low $R_{DS(ON)}$, low gate charge, fast switching, and excellent avalanche characteristics.

This device is specially designed to get better ruggedness and suitable to use in Synchronous-rectification applications.

Features

- Low R_{DS(ON)} & FOM
- Extremely low switching loss
- Excellent stability and uniformity
- Fast switching and soft recovery
- Invertors
- Synchronous-rectification applications

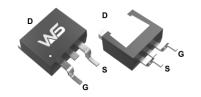
Product Summery

BV _{DSS}	R _{DS(ON)}	I _D
40V	1.5mΩ	200A

Applications

- Consumer electronic power supply
- Motor control
- Synchronous rectification
- Isolated DC
- Synchronous-rectification applications

TO-263-2L Pin Configuration





Absolute Maximum Ratings (T_J=25°C, Unless Otherwise Noted)

Symbol	Parameter	meter Rating	
V_{DS}	Drain-Source Voltage	40	V
V_{GS}	Gate-Source Voltage	±20	V
I _D	Continuous Drain Current ¹	200	۸
I _{DP}	Pulsed Drain Current ²	390	A
E _{AS}	Single Pulse Avalanche Energy ⁴	300	mJ
P_{D}	Power Dissipation ³	140	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	

Thermal Data

Symbol	Parameter	Rating	Units
$R_{ heta JA}$	Thermal Resistance Junction-Ambient ⁵	62	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case	0.89	C/VV

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Electrical Characteristics (T_J=25°C, Unless Otherwise Noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250μA	40			V
В	Statio Dunin Source On Bosistanos	V _{GS} =10V , I _D =55A		1.5	2.0	0
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =4.5V , I _D =55A		2.5	3.0	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250µA	1.3	1.7	2.5	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =40V , V _{GS} =0V			1.0	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA
Q_g	Total Gate Charge			96.8		
Q_{gs}	Gate-Source Charge	V _{DS} =20V , V _{GS} =10V , I _D =20A		14.5		nC
Q_{gd}	Gate-Drain Charge			18.4		
T _{d(on)}	Turn-on Delay Time			26.6		
Tr	Rise Time	V _{DS} =20V , V _{GS} =10V ,		9.3		
$T_{d(off)}$	Turn-off Delay Time	$R_G=2\Omega$, $I_D=20A$		96		ns
T _f	Fall Time			39.3		
C _{iss}	Input Capacitance			6587		
C _{oss}	Output Capacitance	V_{DS} =20V , V_{GS} =0V , f =100KHz		2537		pF
C _{rss}	Reverse Transfer Capacitance			178		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
I _S	Continuous Source Current	V -V -0V Force Current			130	_
I _{SP}	Pulsed Source Current	V _G =V _D =0V, Force Current			390	A
V _{SD}	Diode Forward Voltage	V _{GS} =0V , I _S =20A			1.3	V
t _{rr}	Reverse Recovery Time	L =20.4 di/dt=400.4/up		205		ns
Q_{rr}	Reverse Recovery Charge	- I _S =20A , di/dt=100A/μs		557.4		nC

Note:

- 1. Calculated continuous current based on maximum allowable junction temperature.
- 2. Repetitive rating: pulse width limited by max. junction temperature.
- 3. P_{D} is based on max. junction temperature, using junction-case thermal resistance.
- 4. V_{DD} =30V, R_G =6 Ω , L=0.3mH, starting T_J =25°C.
- 5. The value of $R_{\theta JA}$ is measured with the device mounted on 1 in FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C.



Typical Characteristics

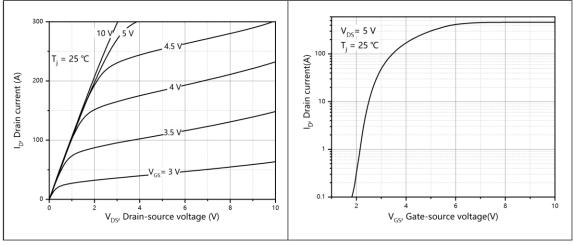


Figure 1, Typ. output characteristics

Figure 2, Typ. transfer characteristics

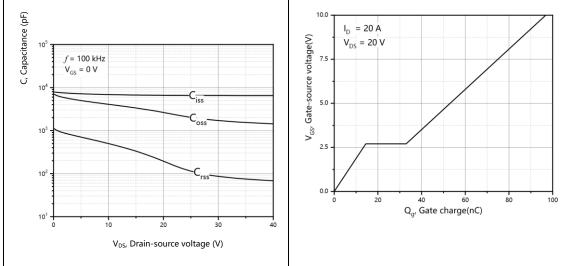


Figure 3, Typ. capacitances

 $I_{\rm D} = 250 \, \mu A$

 $V_{GS} = 0 V$

Drain-source breakdown voltage (V)

BV_{DSS}, 1

Figure 4, Typ. gate charge

| Output |

Figure 5, Drain-source breakdown voltage

T_i, Junction temperature (°C)

Figure 6, Drain-source on-state resistance



Typical Characteristics (Cont.)

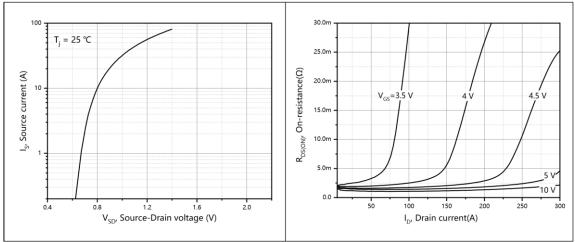


Figure 7, Forward characteristic of body diode

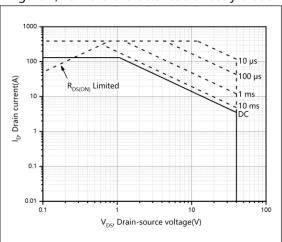
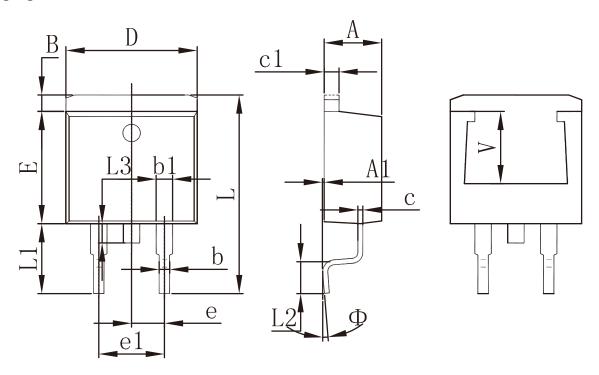


Figure 9, Safe operation area $T_C=25\,^{\circ}C$

Figure 8, Drain-source on-state resistance



Packaging information



SYMBOL	MILLIMETERS		INCHES		
STWIBOL	MIN.	MAX.	MIN.	MAX.	
А	4.470	4.670	0.176	0.184	
A1	0.000	0.150	0.000	0.006	
В	1.120	1.420	0.044	0.056	
b	0.710	0.910	0.028	0.036	
b1	1.170	1.370	0.046	0.054	
С	0.310	0.530	0.012	0.021	
c1	1.170	1.370	0.046	0.054	
D	10.010	10.310	0.394	0.406	
E	8.500	8.900	0.335	0.350	
е	2.540	TYP.	0.100 TYP.		
e1	4.980	5.180	0.196	0.204	
L	14.940	15.500	0.588	0.610	
L1	4.950	5.450	0.195	0.215	
L2	2.340	2.740	0.092	0.108	
L3	1.300	1.700	0.051	0.067	
Ф	0°	8°	0°	8°	
V	5.600	REF.	0.220 REF.		



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